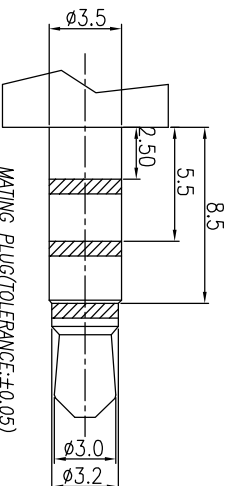
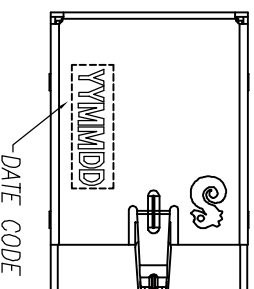
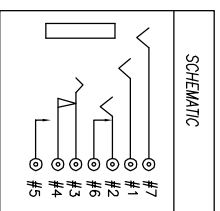


RECOMMENDED PCB LAYOUT (TOP VIEW)  
(TOLERANCE: ±0.05)



MATING PLUG(TOLERANCE:±0.05)  
ø3.5 4-POLE STANDARD PLUG



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
  - CONTACT RESISTANCE: 30mΩ Max..
  - INSULATION VOLTAGE WITHSTAND  
500V AC FOR ONE MINUTE.
  - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
  - LIFE TEST: 5,000 CYCLES Min. (NON-LOAD).
  - INSERTION FORCE: 0.4 - 3.0kg.
  - WITHDRAWAL FORCE: 0.3 - 2.0kg.
  - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ Max..
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ Min..
  - MARKING: MARK "S" ON TOP OF JACK
  - PACKAGING: TAPE & REEL.
  - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
  - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT.
  - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:



REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
A	PDR NO.100927-3A		HM,JIANG	2010.12.16
B	ECN NO.202104-R10		Jinshuai	2021.06.11

I	MYLAR	1	KAPTON	YELLOW
H	SHIELDING	1		ø0.4mm NICKEL Min.
G	TRANSFER TERMINAL	1	COPPER ALLOY 0.2t	1-3µm GOLD PLATING ON CONTACT ARCH
F	MAKE TERMINAL	1		120µm WHITE TIN PLATING ON SOLDER TAIL
E	RING SPRING	1		AND 5µm Min. NICKEL UNDER PLATING.
D	SHUNT TERMINAL-A	1	COPPER ALLOY, 0.25t	20µm Au OVER 50µm NICKEL
C	TIP SPRING	1		20µm Au OVER 50µm NICKEL
B	EARTH	1	COPPER ALLOY 0.2t	30µm GOLD ON CONTACT AND SOLDER TAIL REEL. AND 5µm NICKEL UNDER PLATING.
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.  
信安企業股份有限公司

TITLE: 3.5ø PHONE JACK

DWN: Jinshuai PART NO.2S13018-003311F

CHKD: Bruce SCALE:4:1 UNIT: mm

APVD: Max SIZE: A3 SHEET:1 OF 1 REV: B

CUSTOMER COPY